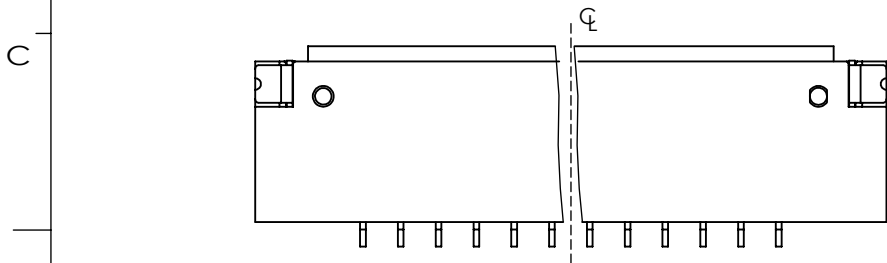
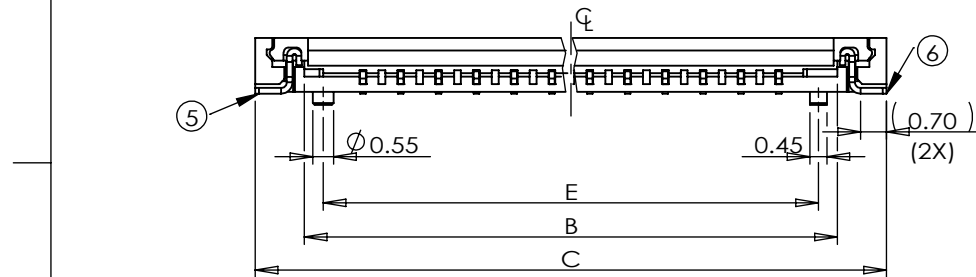
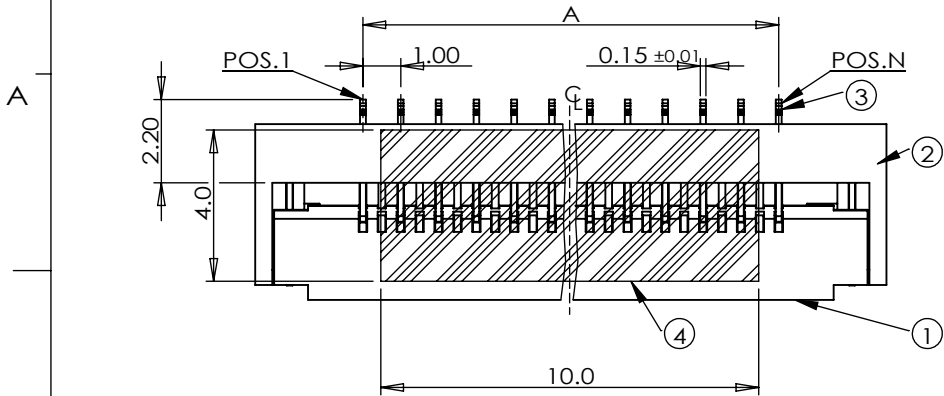


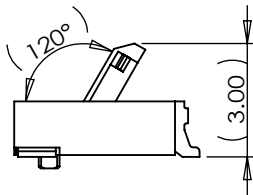
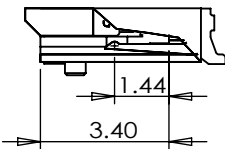
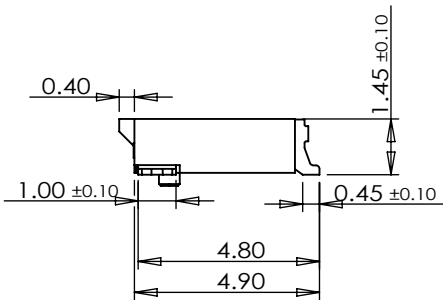
SOLID WORKS GENERATED DRAWING, DON'T CHANGE BY HAND.

REV.	ECN. NO.	APPD.
X1	ECN120504003	Tommy Zhang
X2	ECN120730002	Tommy Zhang
X3	ECN120730004	Tommy Zhang
X4	ECN120801010	Tommy Zhang



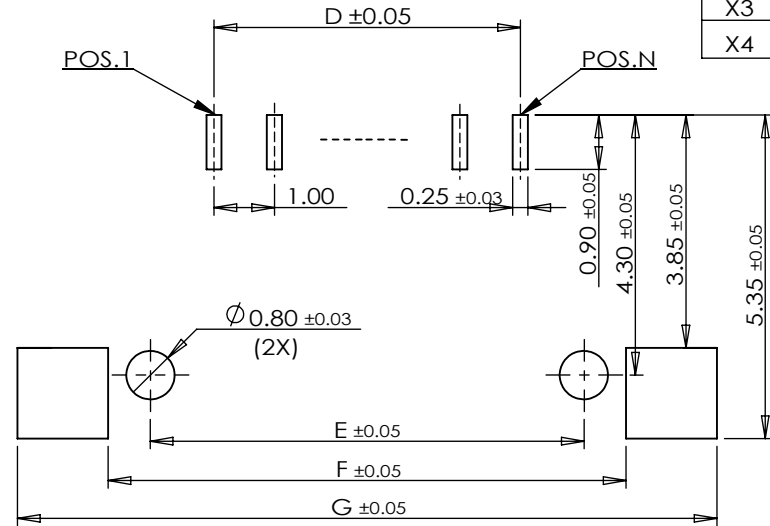
NO. OF CONTACT	A	B	C	D	E	F	G	H
10	9.0	12.1	14.7	9.0	11.1	12.5	15.5	12.0
12	11.0	14.1	16.7	11.0	13.1	14.5	17.5	14.0

NOTES:
1.DIMENSIONS SHOULD BE INTERPRETED PER ASME Y14.5-1994.
2.ELECTRICAL CHARACTERISTICS:
2-1.CONTACT CURRENT RATING:0.5A MAX. PER PIN;
2-2.INSULATION RESISTANCE: 100 MEGAOHMS MIN. AT 500 VDC;
2-3.DIELECTRIC WITHSTANDING VOLTAGE:500 VAC RMS AT 60Hz FOR 1 MINUTE;
2-4.CONTACT RESISTANCE:
50 MINIOHMS MAX. INITIAL.
100 MINIOHMS MAX. AFTER PHYSICAL AND ENVIRONMENTAL TESTS.
3.MECHANICAL CHARACTERISTICS
3-1.DURABILITY:30CYCLES;
4.ENVIRONMENTAL CHARACTERISTICS:
4-1.OPERATING TEMPERATURE: -40'C TO +85'C.
5.THE CONCENTRATIONS OF Br&Cl MUST SATISFY THE REQUIREMENT OF HALOGEN FREE DOCUMENTS.

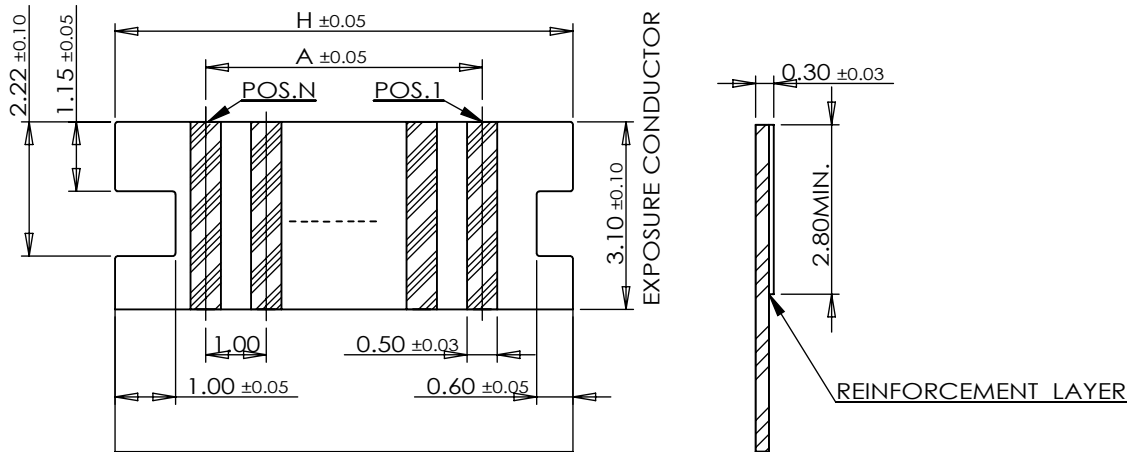


PART NO.
FC1AFNN*-1151H
FPC CONN. PITCH:1=1.0mm
POS.NO.: 10=10POS. 12=12POS.
HALOGEN/LEAD FREE
TAPE & REEL
PROFILE HEIGHT: 15=1.45mm
CONTACT AREA PLATING: 1=GOLD PLATING

PROPOSAL



RECOMMENED PCB LAYOUT



RECOMMENED FPC DIMENSION

⑥	RIGHT PAD	1	STAINLESS STEEL	NICKEL UNDER PLATING; TIN PLATING OVERALL.	
⑤	LEFT PAD	1	STAINLESS STEEL		
④	PI-FILM	1	POLYRESIN		
③	CONTACT	N	COPPER ALLOY	NICKEL UNDER PLATING; GOLD PLATING ON CONTACT AREA; GOLD FLASH ON SOLDER AREA.	
②	HOUSING	1	THERMOPLASTIC		UL, 94V-0
①	ACTUATOR	1	THERMOPLASTIC		UL, 94V-0
ITEM	DESCRIPTION	Q'TY	MATERIAL	TREATMENT	ATTACHMENT

UNITS: mm	GENERAL TOLERANCE		APPROVED: Tommy Zhang	PART NO.(INTENDED USE) FC1AFNN*—1151H
DATE: 7/30'12	X. :±0.30 .X :±0.20 .XX :±0.10 .XXX:±0.05	X* :±2° .X* :±1° .XX* .XXX*	CHECKED: Tommy Zhang	TITLE: CUSTOMER DRAWING
SCALE: 5/1			DRAWING: Walker Zhao	DRAWING NO.: 820—0000—032
SHEET: 1/1	MATERIAL:	Q'TY	Drapho Drapho ELECTRONICS TECHNOLOGY CO., LTD	
REV.: X4	FINISH:			